LNJ411K8YRU

Surface Mounting Chip LED

3216 FD Type

Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Power dissipation	P _D	60	mW	
Forward current	I _F	20	mA	
Pulse forward current *	I _{FP}	100	mA	
Reverse voltage	V _R	4	V	
Operating ambient temperature	T _{opr}	-30 to +85	°C	
Storage temperature	T _{stg}	-40 to +100	°C	

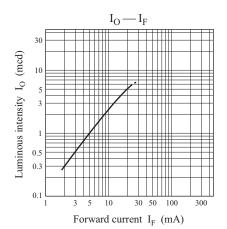
Lighting Color

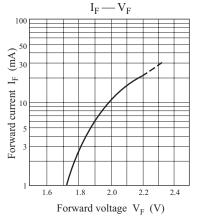
• Amber

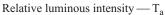
Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

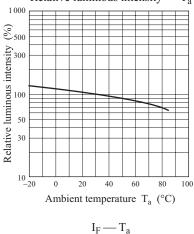
Electro-Optical Characteristics $T_a = 25^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity	I _O	$I_F = 10 \text{ mA}$	0.75	2.2		mcd
Reverse current	I _R	$V_R = 4 V$			10	μΑ
Forward voltage	V _F	$I_{\rm F} = 10 {\rm mA}$		2.0	2.6	V
Peak emission wavelength	$\lambda_{\rm P}$	$I_{\rm F} = 10 {\rm mA}$		590		nm
Spectral half band width	Δλ	$I_{\rm F} = 10 \text{ mA}$		30		nm









40

60

Ambient temperature T_a (°C)

25

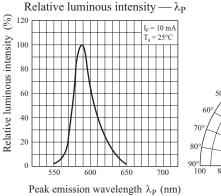
20

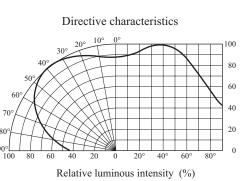
15

10

0

Forward current I_F (mA)







100

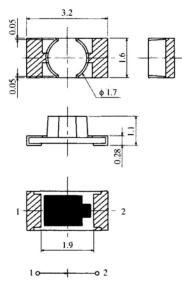
80

LNJ411K8YRU

Panasonic

Package (Unit: mm)

KLTFTN2K1100



• Pin name

1: Anode 2: Cathode

SHD00427BEK

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